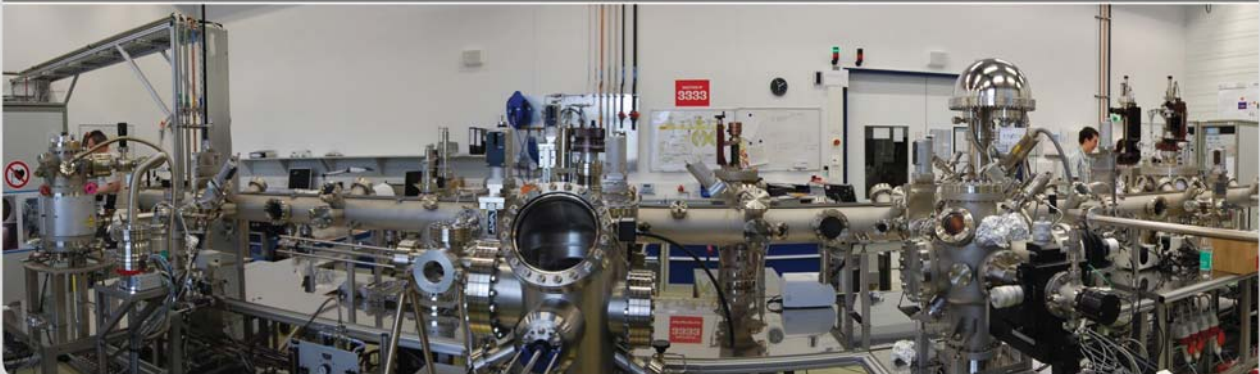


In situ X-Ray Reflectivity measurements during Sputtering of Vanadium Carbide thin films

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ANKA / Institut für Synchrotronstrahlung (ISS)



KIT – University of the State of Baden-Württemberg and
National Large-scale Research Center of the Helmholtz Association

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Content

- Motivation

- *In situ* X-Ray Reflectivity

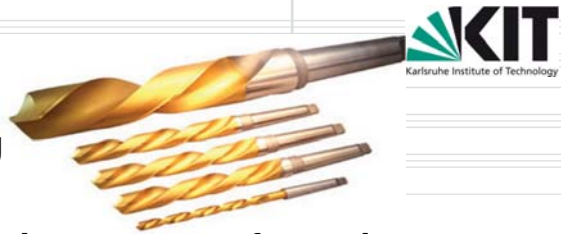
- Three Examples:
 - *In situ* XRR @ T=125 °C
 - *In situ* XRR at different DC Power
 - Interruption of Deposition

- Summary & Outlook

Motivation

Vanadium Carbide (VC_{1-x})

- Growth of thin films by Sputtering
- Hard coating material for tools



deposition conditions → microstructure formation

→ mechanical properties

→ Understand growth process depending on sputtering conditions

→ Investigation needs suitable methods

- nondestructive monitoring of growth process
- resolution in **sub-nanometer scale**
- compatibility with the **gas atmosphere**
- investigation of
 - polycrystalline material
 - high deposition rates (0.22 nm/s @ DC Power 200 W)

➔ **In situ X-Ray Reflectivity**

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14.05.2012

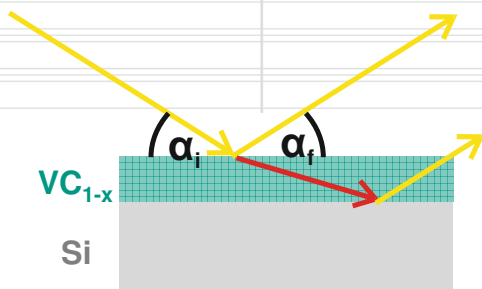
E-MRS Spring Meeting 2012, M. Kaufholz

In situ X-Ray Reflectivity measurements during Sputtering of Vanadium Carbide thin films

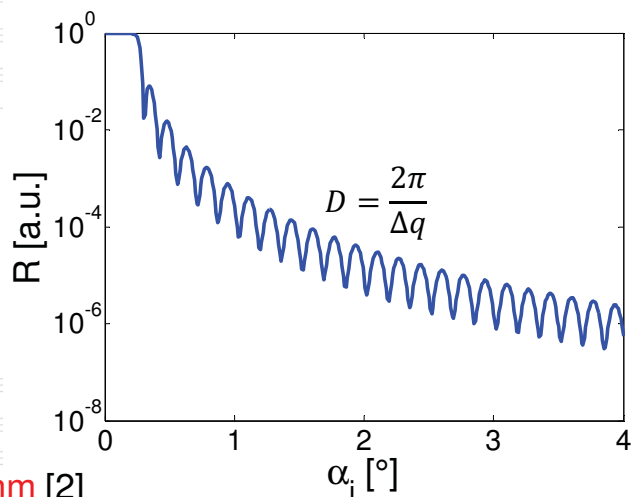


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Basics of X-Ray Reflectivity



- Electron density ('Critical Angle')
- Thickness ('Kiessig fringes')
- Roughness ('Slope') [1]
- Description by Parratt-Algorithm [2]
 - Fully dynamical description of XRR



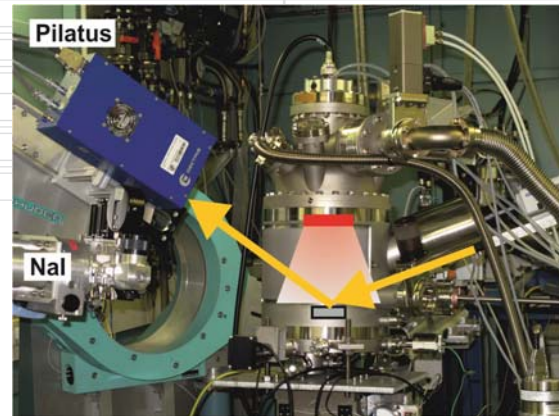
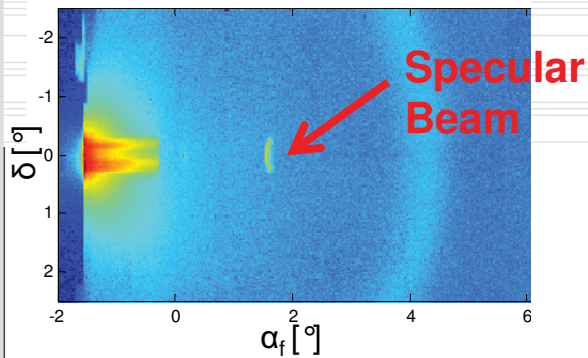
➔ **Two options** to measure *in situ* XRR

1. Full angular range XRR
2. XRR at a fixed angular position

[1] Pietsch, Holy, Baumbach, *High Resolution X-Ray Scattering from thin films and lateral Nanostructures*, Springer 2004

[4] Parratt, *Phys. Rev.* 95, 2, p. 359-369, (1954)

Experimental Setup



■ Setup @ MPI-Beamline:

- Energy: 10 keV
- Beamsize: 300µm x 200µm
- Optics
 - Resolution in q_z : $\sim 0.005 \text{ \AA}^{-1}$
- Detector: Pilatus 1000K
 - Resolution in time: $\sim 1.1\text{-}2.3 \text{ s}$

■ Sputter conditions [1]:

- Target: VC_{1-x}
- Substrate: Si(100) with natural oxide
- Target-substrate Distance: 10 cm
- Argon Pressure: $2 \times 10^{-3} \text{ mbar}$
- Deposition rate 0.22 nm/s@ 200 W

[1] Krause et al., J. Synchrotron Rad. (2012), **19**, 216-222

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In situ X-Ray Reflectivity measurements during Sputtering of Vanadium Carbide thin films

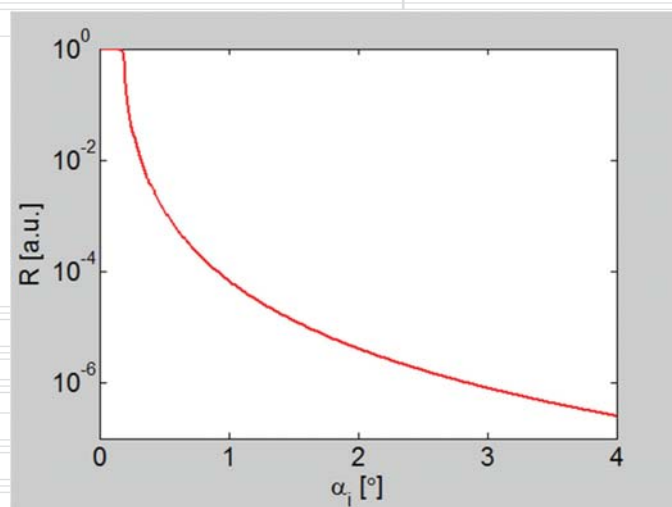
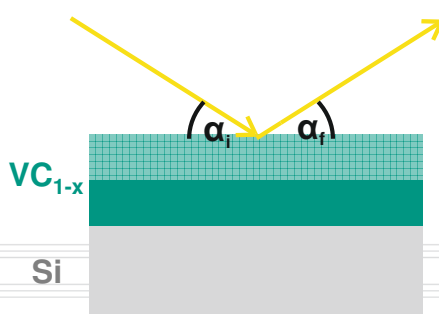


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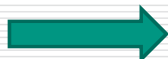
In situ X-Ray Reflectivity: “full angular range”



■ Measure full angular range



- High deposition rate of 0.22 nm @ 200 W \rightarrow $\sim 90\text{nm}$ deposition/XRR
- Possible electron density and roughness changes



Interpretation of XRR curve difficult

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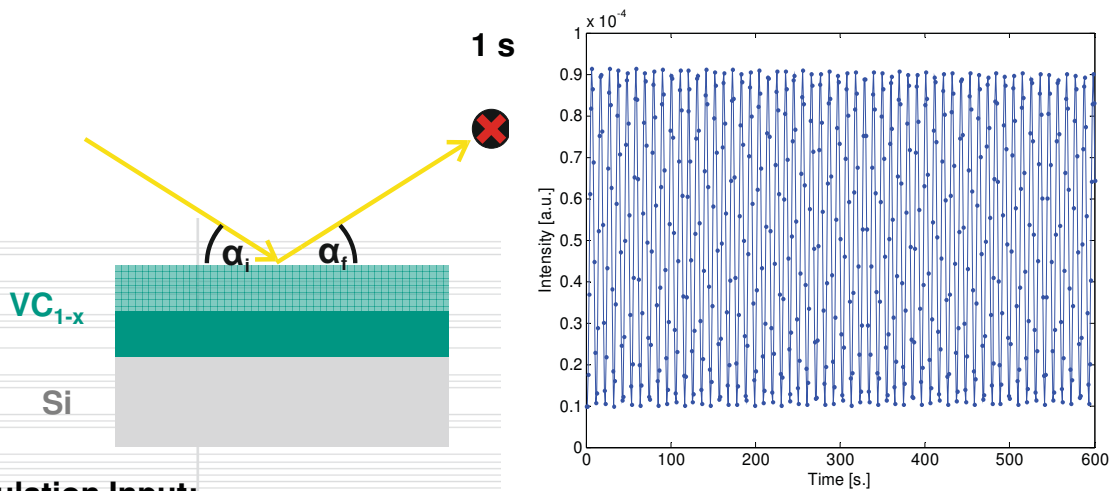
In situ X-Ray Reflectivity measurements during Sputtering of Vanadium Carbide thin films



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In situ X-Ray Reflectivity: "fixed angular position"

- Detector and sample are at a **fixed angular position** ($\alpha_i = 1.6^\circ$)
- Measuring Pre- and Post-growth full angular range XRR



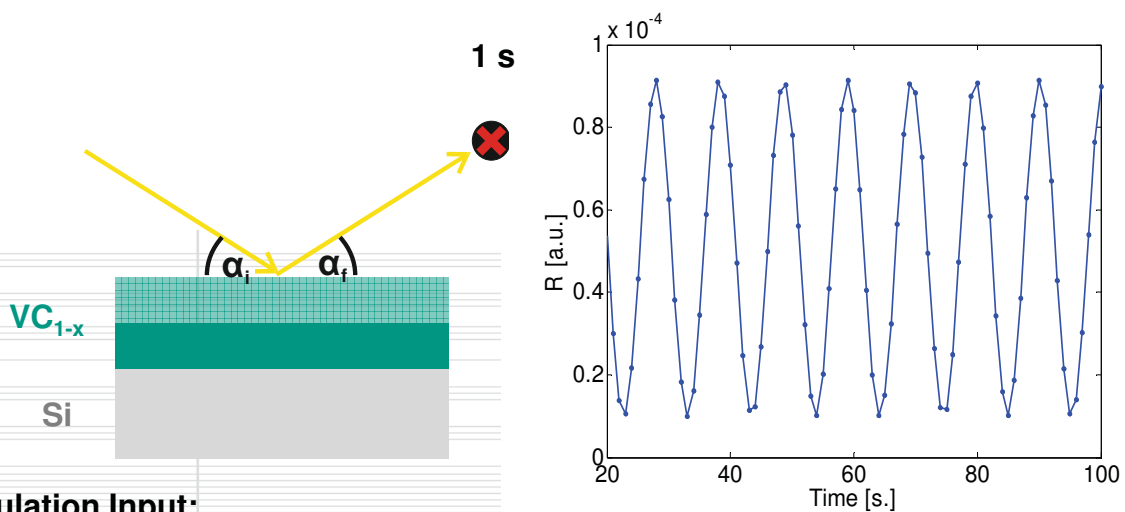
Simulation Input:

DC Power: 200 W \rightarrow Deposition Rate: 0.217 nm/s

$$\alpha_i = 1.6^\circ$$

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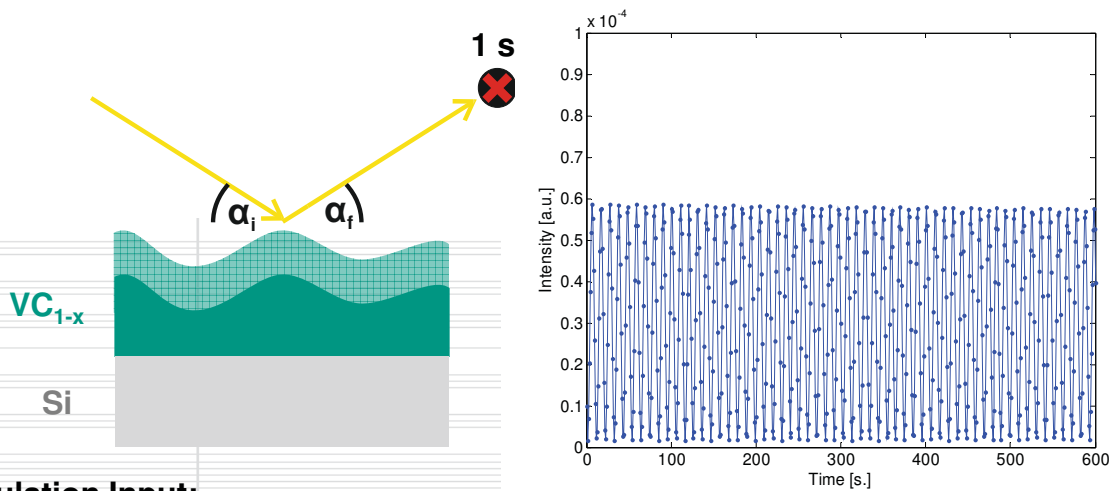
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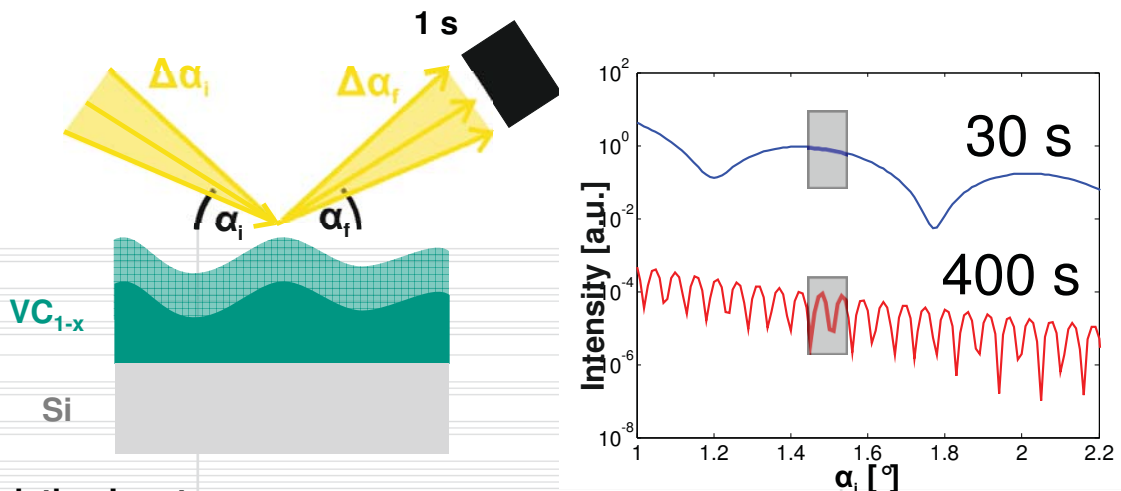
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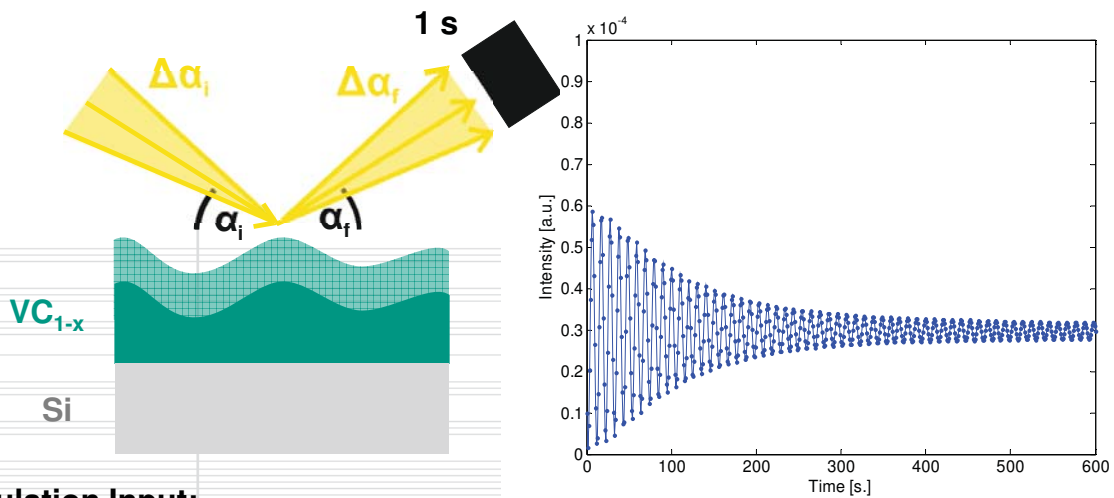
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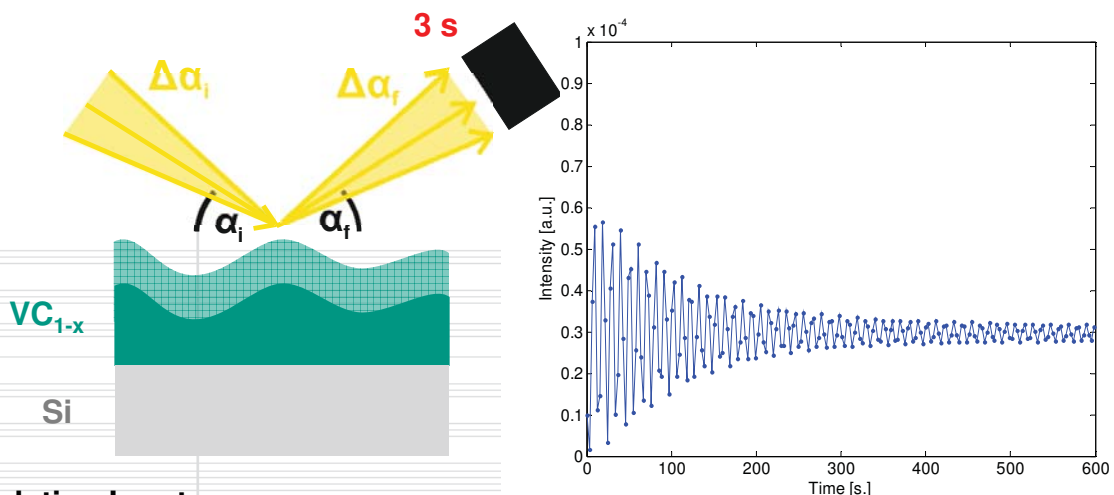
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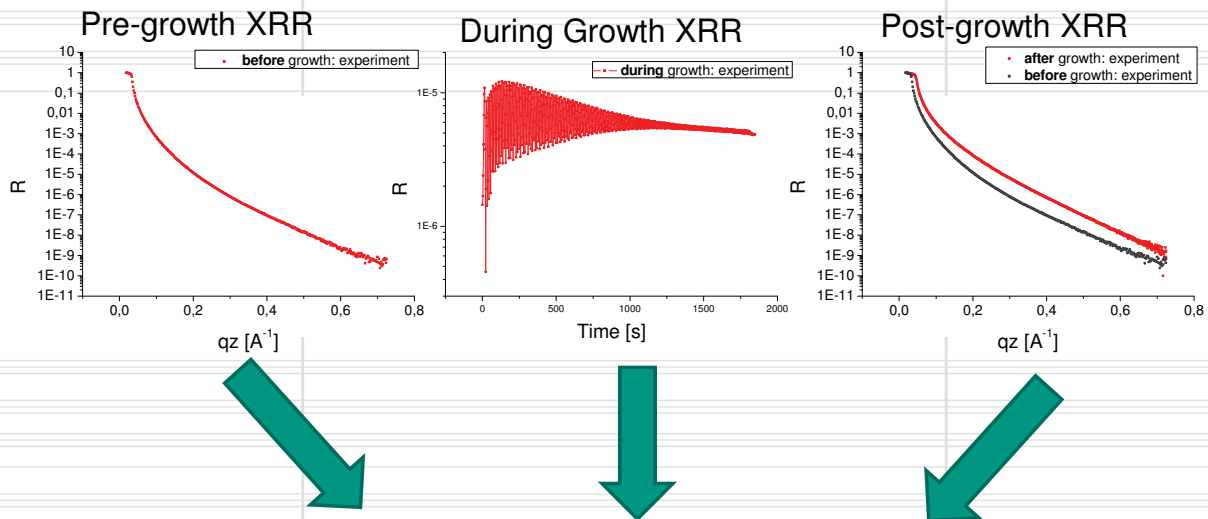


Simulation Input:

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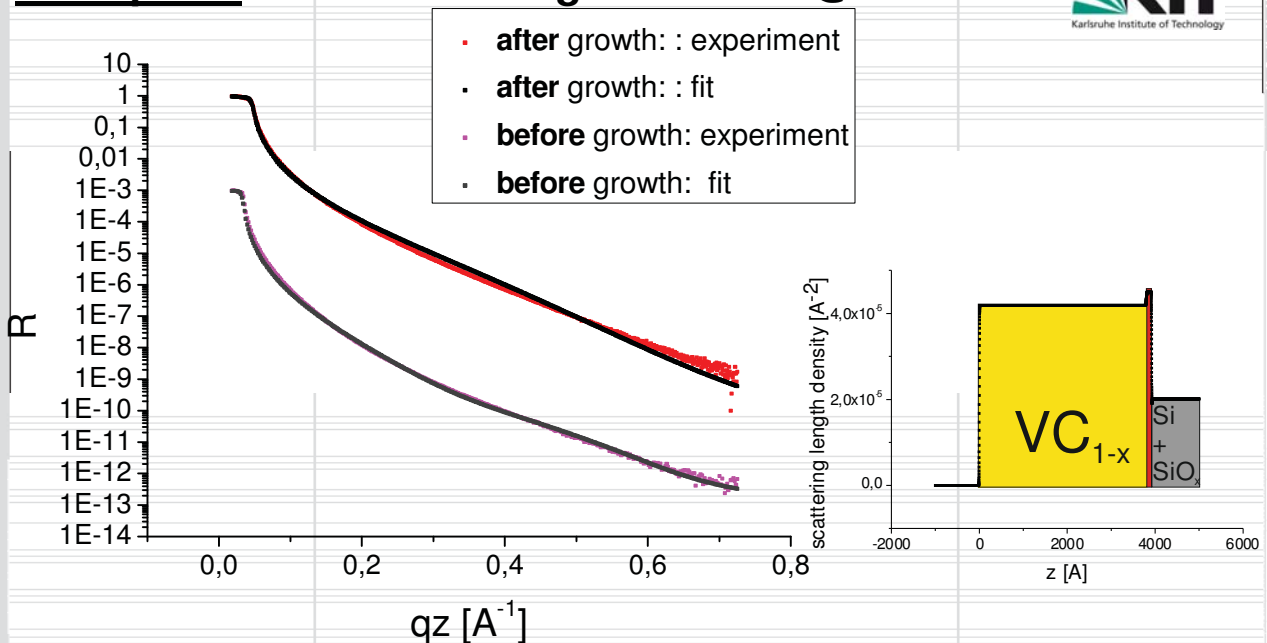
$$\alpha_i = 1.6^\circ$$

Example 1: In situ XRR Study @ T=125°C



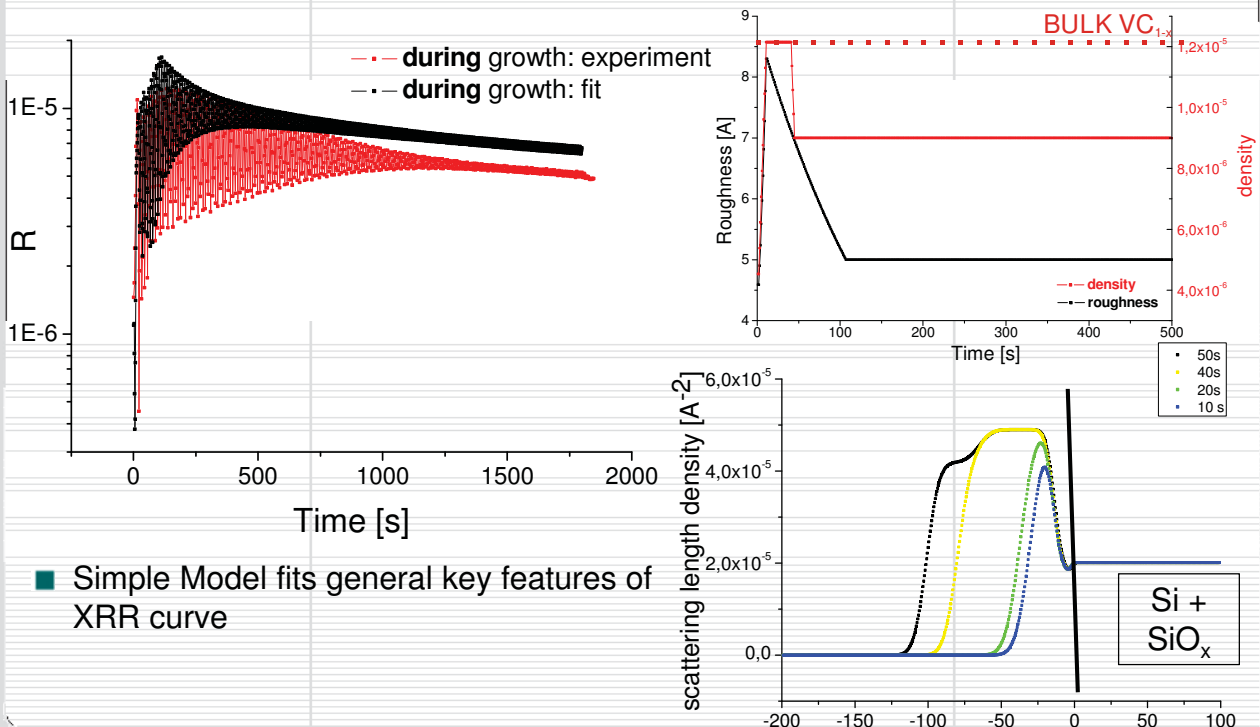
Need of **one** model, which fits **all three** curves

Example 1: Pre- and Post-growth XRR @ T=125°C



- Interface layer of ~ 6 nm: Bulk-like electron density
- ~ 3800 nm of less dense VC_{1-x} (~90%)
- Different porosities, random and textured polycrystalline layer

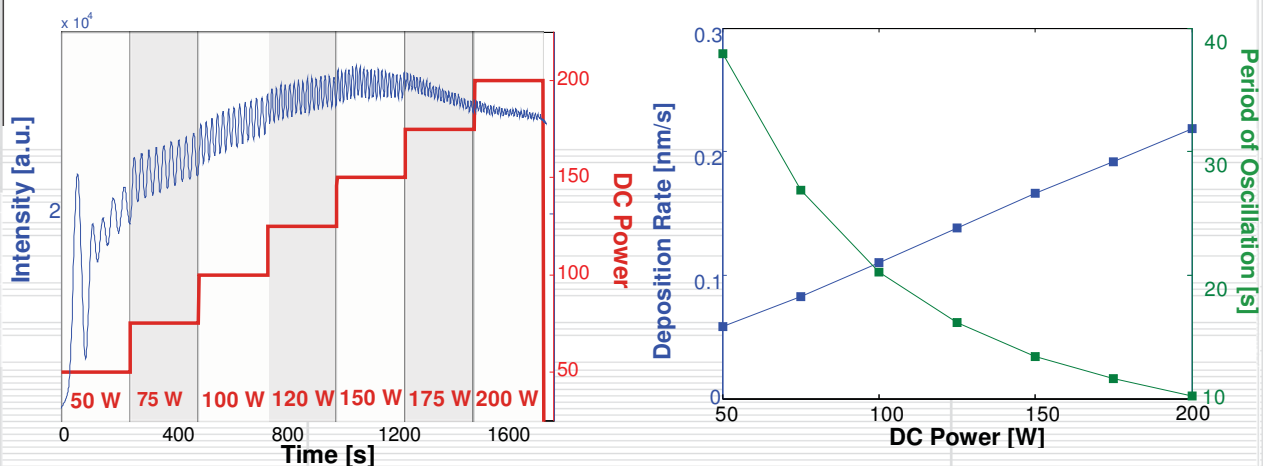
Example 1: *In situ* XRR @ T=125°C : Monitoring of Roughness and Density



■ Simple Model fits general key features of XRR curve

Example 2: Determination of Deposition Rate depending on DC Power at RT

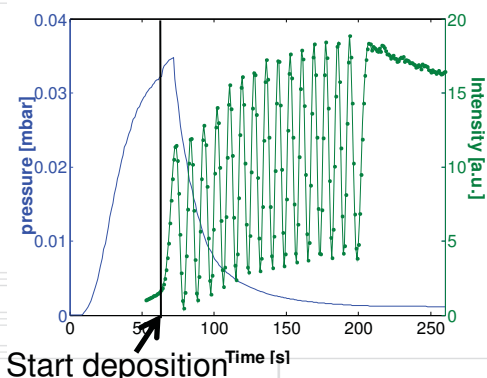
- Increase of DC Power by $\Delta P = 25W$ every 250s
- $\alpha_i = 1.6^\circ$:
 - Error due to changes in electron density < 1%
 - Sensitive to deposition rate



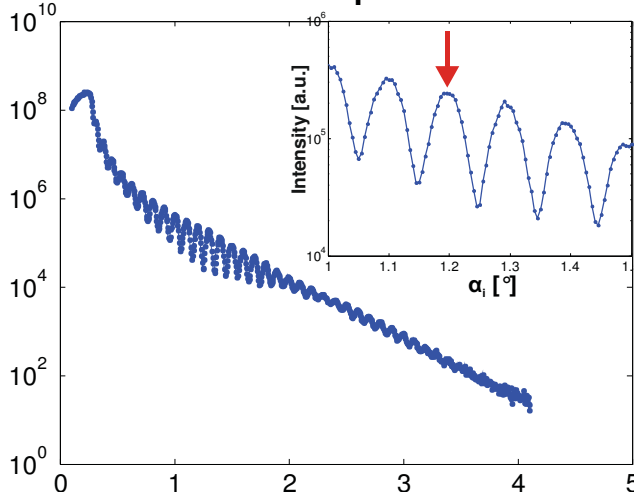
→ Deposition Rate \sim DC Power

Example 3: Different Electron Densities due to Interruption of Deposition

- Interruption of deposition after 200s @ RT and DC Power of 200 W

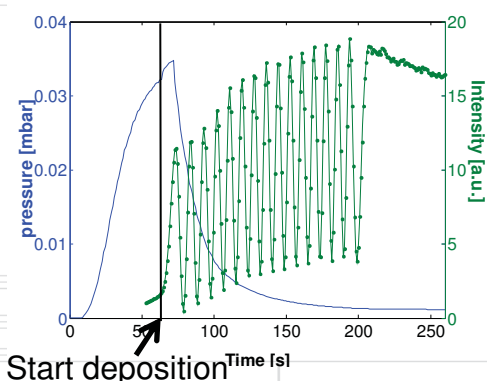


XRR after 1. deposition:

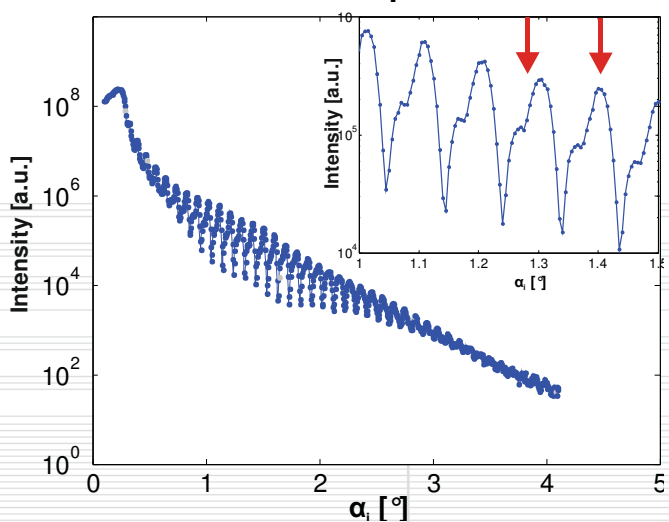


Example 3: Different Electron Densities due to Interruption of Deposition

- Interruption of deposition after 200s @ RT and DC Power of 200 W



XRR after 2. deposition:



Multilayer of one material

Summary

- *In situ* X-Ray Reflectivity is suitable for investigation of VC_{1-x}
 - Sensitive to
 - **Deposition Rate**
 - **Roughness**
 - **Density**
 - Sensitive to different sputtering conditions

Outlook

- Simulation of *in situ* XRR curves
 - Growth Model (Scaling law)
 - Include diffuse scattering
 - Limits of method
- Combining with other methods for a better understanding
 - *In situ* & *ex situ* X-Ray Diffraction and Absorption Spectroscopy
 - XPS, AFM, TEM, ... (in UHV conditions)
 - Measuring Hardness via Nano-/Microindentation

Acknowledgements

- M. Mantilla for technical support @ MPI Beamline @ ANKA
- H. Gräfe for technical support @ UHVLab @ ANKA
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Thank You for Your Attention !